

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A heating assembly with at least one PTC element, in particular for a motor vehicle, the PTC element (2) being arranged between contact plates (3,4) which serve for making electrical connection, the contact plates (3,4) and the PTC element (2) being bonded by means of an adhesive (5), ~~characterized in that~~ wherein the adhesive (5) has a resistivity of at least 50 ohms × cm and at most 500 ohms × cm.
2. (Currently amended) The heating assembly as claimed in claim 1, ~~characterized in that~~ wherein the adhesive (5) has a resistivity of at least 80 ohms × cm and at most 150 ohms × cm, in particular of 100 ohms × cm +/- 10%.
3. (Currently amended) The heating assembly as claimed in claim 1 or 2, ~~characterized in that~~ wherein the layer thickness of the adhesive (5) between the PTC element (2) and a contact plate (3,4) before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm, in particular 0.01 μm +/- 10%.
4. (Currently amended) A heating assembly with at least one PTC element, in particular for a motor vehicle, the PTC element (2) being arranged between contact plates (3,4) which serve for making electrical connection, the contact plates (3,4) and the PTC element (2) being bonded by means of a solder, ~~characterized in that~~ wherein the solder has a resistivity of at least 50 ohms × cm and at most 500 ohms × cm.
5. (Currently amended) The heating assembly as claimed in claim 4, ~~characterized in that~~ wherein the solder has a resistivity of at least 80 ohms × cm and at most 150 ohms × cm, in particular of 100 ohms × cm +/- 10%.

6. (Currently amended) The heating assembly as claimed in ~~claim 4 or 5, characterized in that claim 4, wherein~~ the layer thickness of the solder between the PTC element (2) and a contact plate (3, 4) before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm , in particular 0.01 μm +/- 10%.
7. (Currently amended) An adhesive or a solder for bonding between a ceramic PTC element (2) and an electrically conducting contact plate (3, 4), characterized in that the adhesive (5) or the solder has a resistivity of at least 50 ohms \times cm and at most 500 ohms \times cm.
8. (New) The heating assembly as claimed in claim 2, wherein the layer thickness of the adhesive between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm , in particular 0.01 μm +/- 10%.
9. (New) The heating assembly as claimed in claim 5, wherein the layer thickness of the solder between the PTC element and a contact plate before enforced relaxation is negligible and after enforced relaxation is at most 0.02 μm , in particular 0.01 μm +/- 10%.